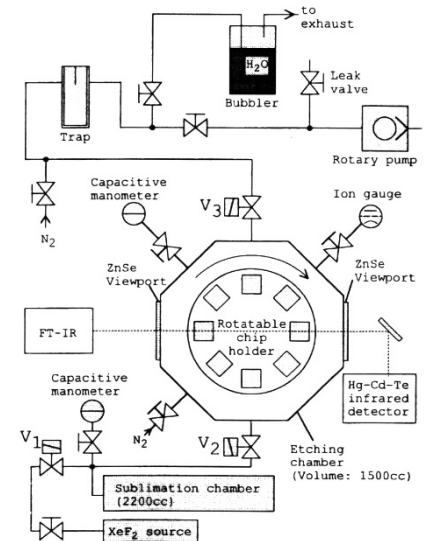
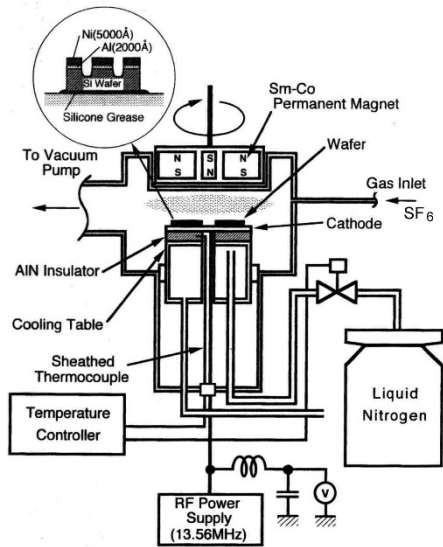


5 Micromachining and packaging

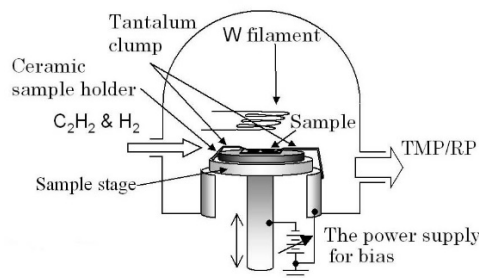
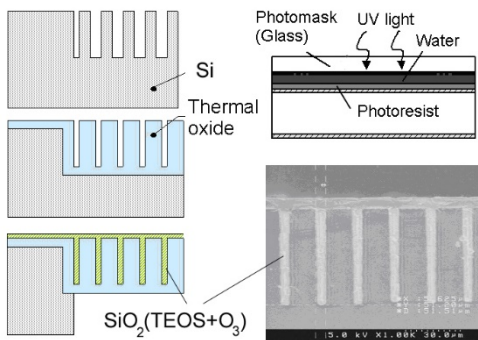


Deep RIE system and resonating gyro fabricated using it

Si etching system using XeF_2

(M.Takinami, Tech. Digest of the 11th Sensor Symp. (1992) 15)

(R.Toda, Sensors & Actuators, A66(1998) 268)

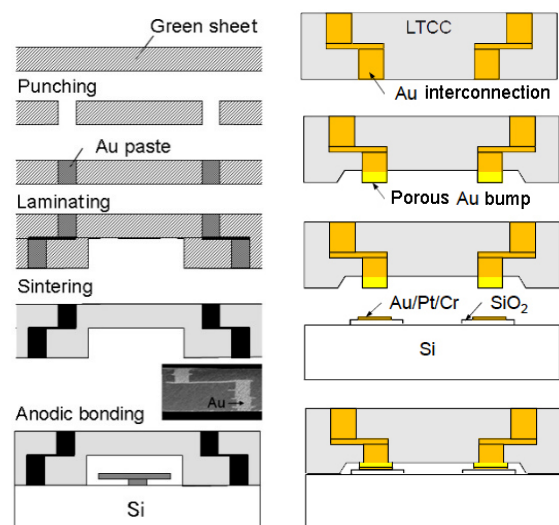
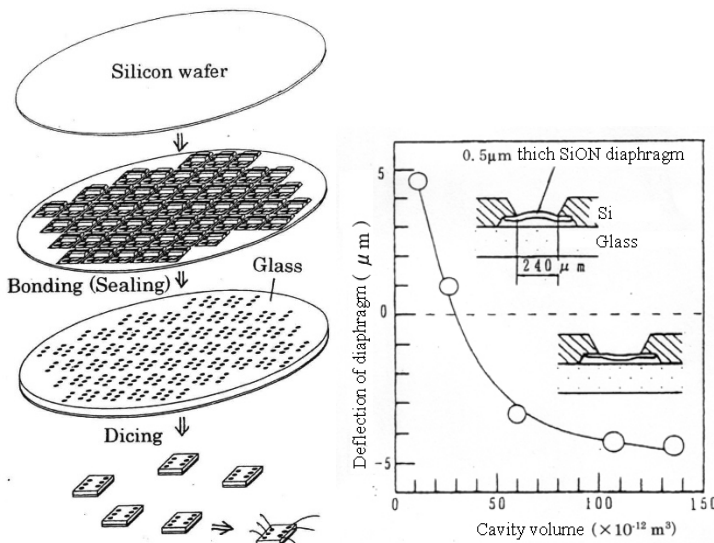


Water immersion contact lithography and trench refill.

Hot filament CVD used for Carbon nanotube growth (or diamond film deposition).

(K.S.Chang, et.al, J.of Micromech. Microeng., 15 (2005) S171)

(T.Ono et.al., Nanotechnology, 13 (2002) 62–64)



Wafer level packaging (WLP). O_2 generation during anodic bonding. WLP using LTCC with electrical feedthrough.

(M.Esashi, J.of Micromech. and Microeng., 18 (2008) 073001) (S.Tanaka et.al., Technical Digest IEEE MEMS, (2012) 369)